



PATENT

Case Docket No. ASMJP.062AUS

Date: June 27, 2002

Page 1

In re application of : Kyogoku, et al.
App. No. : 09/650,122
Filed : August 29, 2000
For : SEALING MECHANISM OF
MULTI-CHAMBER LOAD-
LOCKING DEVICE
Examiner : R. Kackar
Art Unit : 1763

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(Date)

Gordon H. Olson
Gordon H. Olson, Reg. No. 20,319

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UNITED STATES PATENT AND TRADEMARK OFFICE
P.O. Box 2327
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

CLAIMS AS FILED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	9	—	20	= 0 ×	\$18	= \$0
Independent Claims	2	—	3	= 0 ×	\$84	= \$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0	

- (X) Amendment in nine (9) pages.
(X) Return prepaid postcard.
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	:	Kyogoku et al.)	Group Art Unit 1763
)	
Appl. No.	:	09/650,122)	
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Filed	:	August 29, 2000)	
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		MULTI-CHAMBER LOAD-)	
		LOCKING DEVICE)	
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Examiner	:	R. Kackar)	

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AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

In response to the Office Action mailed April 3, 2002 (Paper number 4), please amend the above-captioned application as follows:

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 6, line 5, with the following rewritten paragraph:

-- Figure 1(b) shows a position where the plate 2 is at the highest position and seals the sealing surface 13. As a result, the load-locking chamber 1 is divided into two chambers (15, 16). The two chambers have no airflow. Semiconductor wafers 9 are brought in via the gate valve 10 from the load stations to the first chamber 15. At this time, a pressure within the first chamber 15 is atmospheric pressure. The gate valve 11 of the second chamber is shut and the air is exhausted by a vacuum pump (not shown). At this time, force generated by a pressure difference between the two chambers acts in the direction from the first chamber to the second chamber. The second chamber 16 is connected with the transfer chamber (not shown). As shown in the figure, the volume in the second chamber is greater than that in the first chamber. --

IN THE CLAIMS:

Please amend Claims 1, 3, 4 and 6-8 as follows: